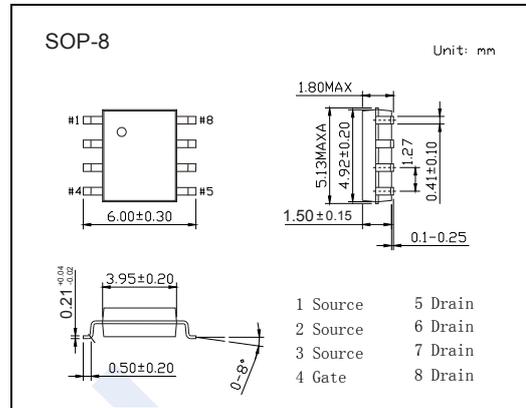
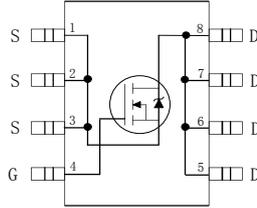


N-Channel MOSFET

IRF7855 (KRF7855)

■ Features

- $V_{DS} (V) = 60V$
- $I_D = 12 A (V_{GS} = 10V)$
- $R_{DS(ON)} < 9.4m\Omega (V_{GS} = 10V)$



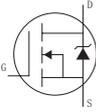
■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	$TA=25^\circ C$	12
		$TA=70^\circ C$	8.7
Pulsed Drain Current	I_{DM}	97	A
Power Dissipation	P_D	2.5	W
Linear Derating Factor		0.02	$W/^\circ C$
Avalanche Current	I_{AS}	7.2	A
Single Pulse Avalanche Energy	E_{AS}	540	mJ
Peak Diode Recovery dv/dt	dv/dt	9.9	V/ns
Thermal Resistance.Junction- to-Ambient	R_{thJA}	50	$^\circ C/W$
Thermal Resistance.Junction- to-Case	R_{thJC}	20	
Junction Temperature	T_J	150	$^\circ C$
Storage Temperature Range	T_{stg}	-55 to 150	

N-Channel MOSFET

IRF7855 (KRF7855)

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V _{DSS}	I _D =250 μ A, V _{GS} =0V	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			20	μ A
		V _{DS} =60V, V _{GS} =0V, T _J =125°C			250	
Gate-Body Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =100 μ A	3		4.9	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =12A		7.4	9.4	mΩ
Forward Transconductance	g _{FS}	V _{DS} =25V, I _D =7.2A	14			S
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =25V, f=1MHz		1560		pF
Output Capacitance	C _{oss}			440		
Reverse Transfer Capacitance	C _{rss}			120		
Output Capacitance	C _{oss}	V _{GS} = 0V, V _{DS} = 1V, f = 1.0MHz		1910		
Output Capacitance	C _{oss}	V _{GS} = 0V, V _{DS} = 48V, f = 1.0MHz		320		
Effective Output Capacitance	C _{oss eff}	V _{GS} = 0V, V _{DS} = 0 to 48V		520		
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =30V, I _D =7.2A		26	39	nC
Gate Source Charge	Q _{gs}			6.8		
Gate Drain Charge	Q _{gd}			9.6		
Turn-On DelayTime	t _{d(on)}	V _{GS} =10V, V _{DS} =30V, I _D =7.2A, R _G =6.2 Ω		8.7		ns
Turn-On Rise Time	t _r			13		
Turn-Off DelayTime	t _{d(off)}			16		
Turn-Off Fall Time	t _f			12		
Body Diode Reverse Recovery Time	t _{rr}	I _S = 7.2A, V _{GS} =0, di/dt= 100A/μ s, T _J = 25°C		33	50	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 7.2A, V _{DD} =25V, di/dt= 100A/μ s, T _J = 25°C		38	57	nC
Maximum Body-Diode Continuous Current	I _S	MOSFET symbol showing the integral reverse p-n junction diode. 			2.3	A
Pulsed Source Current	I _{SM}					
Diode Forward Voltage	V _{SD}	I _S = 7.2A, V _{GS} =0, T _J = 25°C		0.71	1.3	V

N-Channel MOSFET IRF7855 (KRF7855)

■ Typical Characteristics

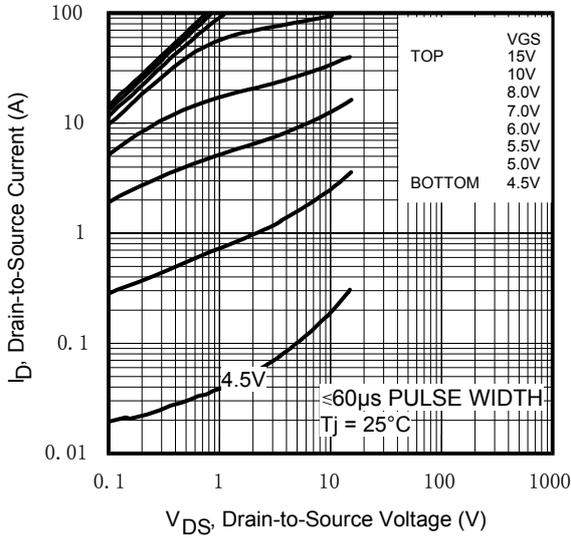


Fig 1. Typical Output Characteristics

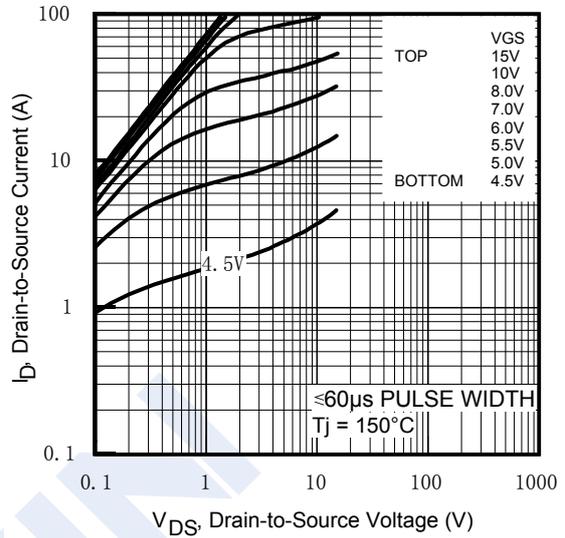


Fig 2. Typical Output Characteristics

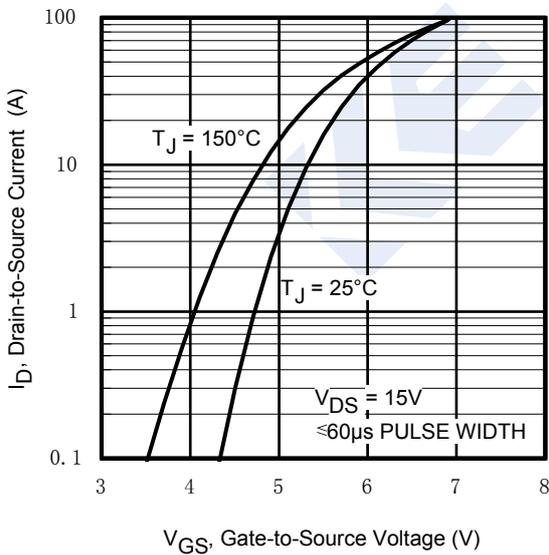


Fig 3. Typical Transfer Characteristics

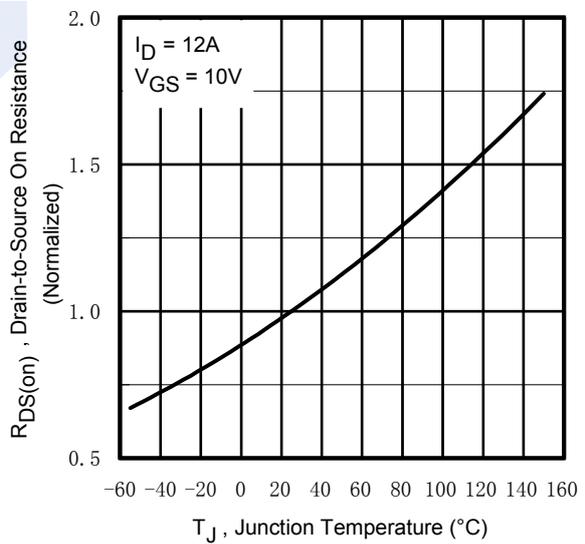


Fig 4. Normalized On-Resistance vs. Temperature

N-Channel MOSFET IRF7855 (KRF7855)

■ Typical Characteristics

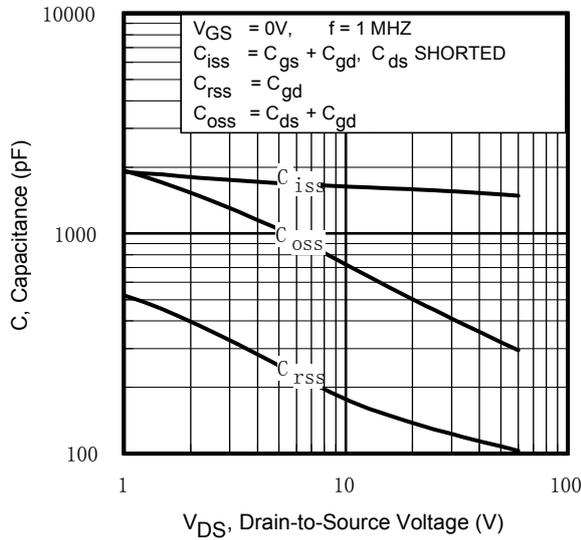


Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

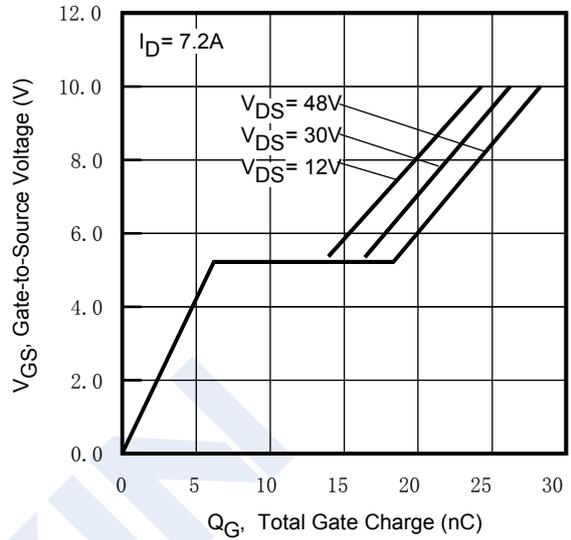


Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

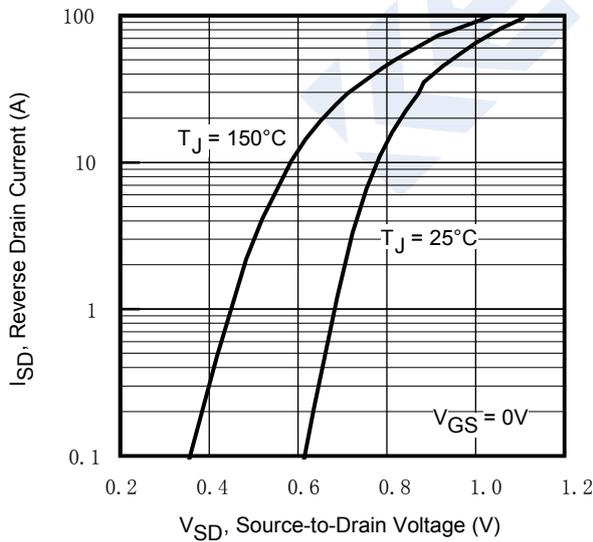


Fig 7. Typical Source-Drain Diode Forward Voltage

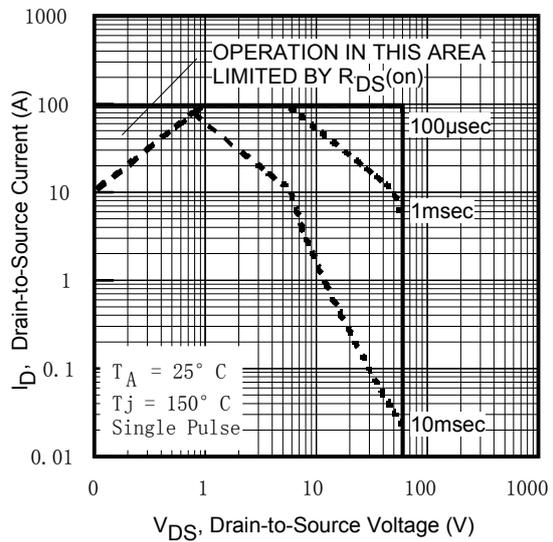


Fig 8. Maximum Safe Operating Area

N-Channel MOSFET IRF7855 (KRF7855)

■ Typical Characteristics

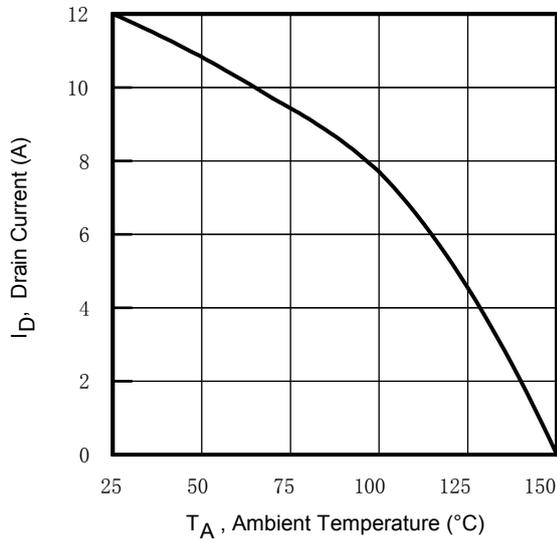


Fig 9. Maximum Drain Current vs. Ambient Temperature

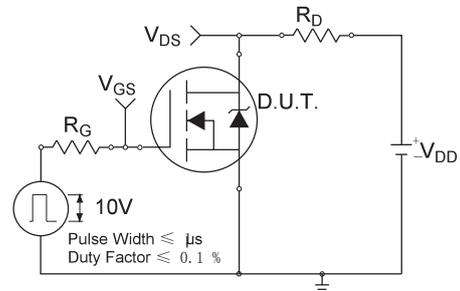


Fig 10a. Switching Time Test Circuit

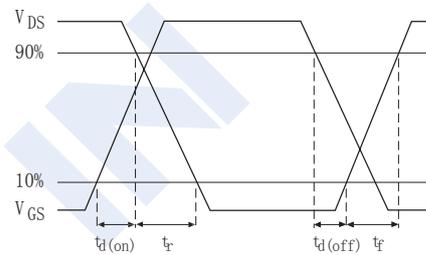


Fig 10b. Switching Time Waveforms

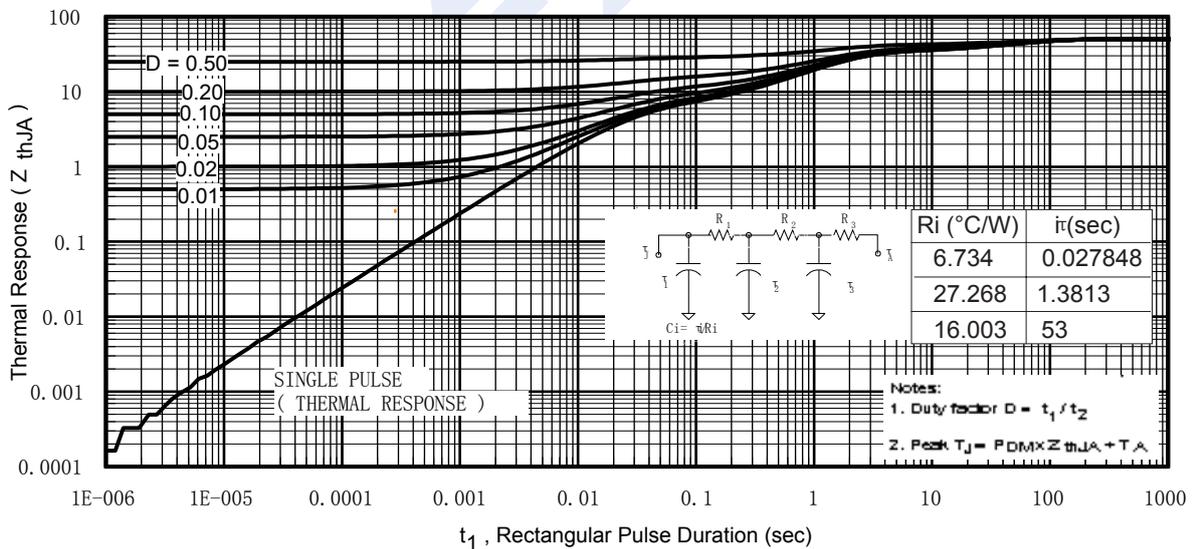


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

N-Channel MOSFET IRF7855 (KRF7855)

■ Typical Characteristics

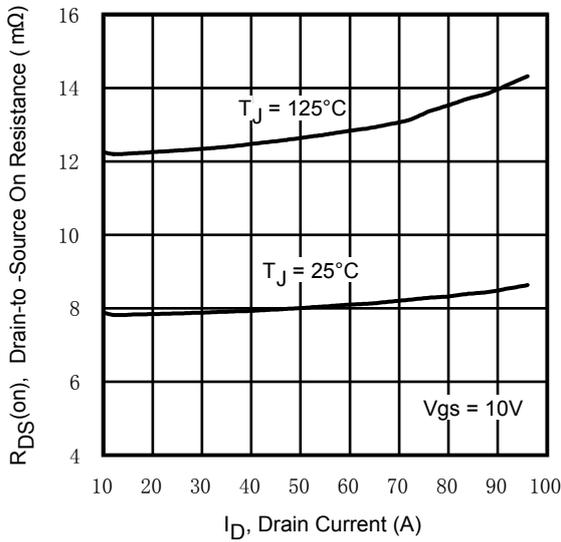


Fig 12. On-Resistance vs. Drain Current

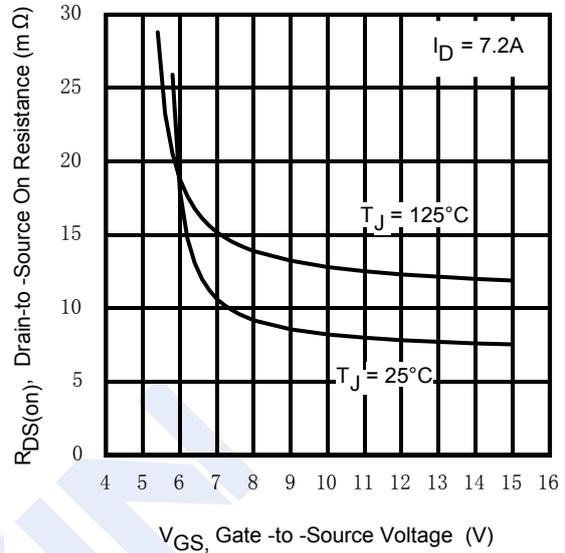


Fig 13. On-Resistance vs. Gate Voltage

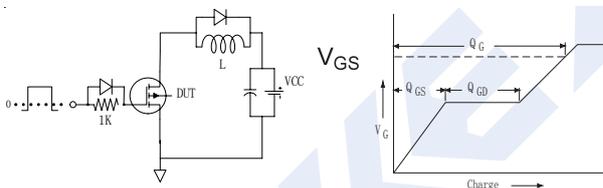


Fig 14a&b. Basic Gate Charge Test Circuit and Waveform

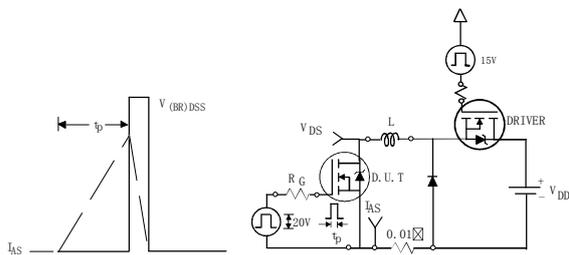


Fig 15a&b. Unclamped Inductive Test circuit and Waveforms

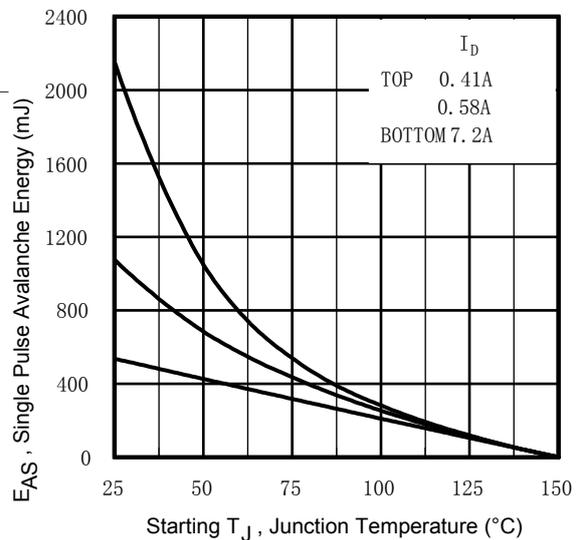


Fig 15c. Maximum Avalanche Energy vs. Drain Current